

C1808X511JGGACTU

Specifications

Insulation Resistance

Aliases (C1808X511JGGAC7800) SMD Comm COG HV Flex, Ceramic, 510 pF, 5%, 2,000 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 1808, 2.9 mm



General Information	
Series	SMD Comm COG HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra- Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	81 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1808
L	4.7mm +/-0.5mm
W	2mm +/-0.2mm
Т	1.6mm +/-0.15mm
S	2.9mm MIN
В	0.7mm +/-0.35mm

	Capacitance	510 pF
	Measurement Condition	1 MHz 1.0Vrms
	Tolerance	5%
	Voltage DC	2000 VDC
	Dielectric Withstanding Voltage	2,400 VDC
	Temperature Range	-55/+125°C
	Temp. Coefficient	COG
_	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
	Dissipation Factor	0.1% 1 MHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour

100 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

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